



Docket No.: M4065.0018/P018-A
(PATENT)

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:
Rodney C. Langley, et al.

Application No.: 09/507,465

Group Art Unit: 1765

Filed: February 22, 2000

Examiner: M. Anderson

For: **METHOD AND APPARATUS FOR
PLASMA ETCHING A WAFER**

AMENDMENT

MS Non-Fee Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

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OCT 10 2003
TC 1700

Dear Sir:

In response to the Office Action dated August 5, 2003 (Paper No. 27), please amend the above-identified U.S. Patent application as follows.